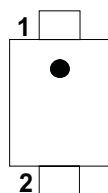


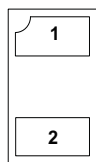
SP1003 Series - 30pF 30kV Unidirectional Discrete TVS



Pinout



SOD723



SOD882

Functional Block Diagram



Description

Zener diodes fabricated in a proprietary silicon avalanche technology protect each I/O pin to provide a high level of protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust diodes can safely absorb repetitive ESD strikes at $\pm 30\text{kV}$ (contact discharge, IEC 61000-4-2) without performance degradation. Additionally, each diode can safely dissipate 7A of 8/20 μs surge current (IEC61000-4-5) with very low clamping voltages.

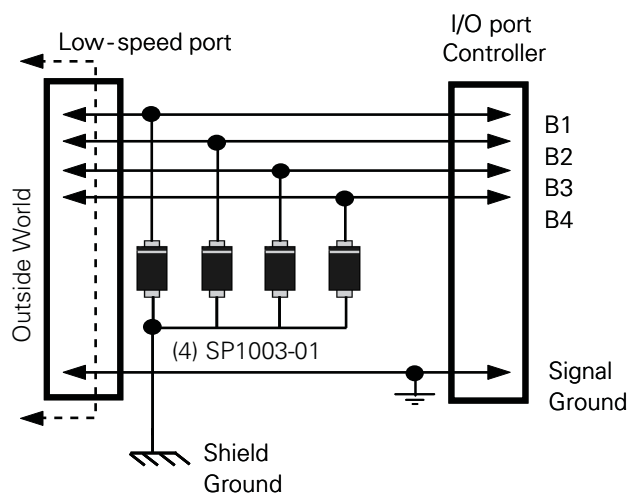
Features

- ESD, IEC61000-4-2, $\pm 30\text{kV}$ contact, $\pm 30\text{kV}$ air
- EFT, IEC61000-4-4, 40A (5/50ns)
- Lightning, IEC61000-4-5, 7A (8/20 μs)
- Low leakage current of 100nA (MAX) at 5V
- Tiny SOD723/ SOD882 (JEDEC MO-236) package saves board space
- Fits solder footprint of industry standard 0402 (1005) devices

Applications

- Mobile phones
- Smart phones
- PDAs
- Portable navigation devices
- Digital cameras
- Portable medical devices

Application Example



Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Pulse Current ($t_p=8/20\mu s$)	7.0	A
T_{OP}	Operating Temperature	-40 to 85	°C
T_{STOR}	Storage Temperature	-60 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

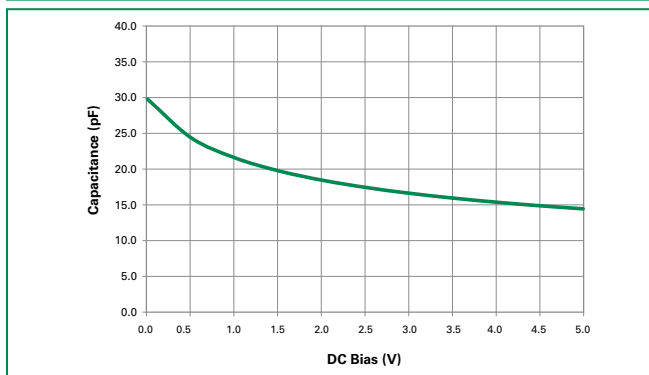
Parameter	Rating	Units
Storage Temperature Range	-65 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

Electrical Characteristics ($T_{OP}=25^{\circ}C$)

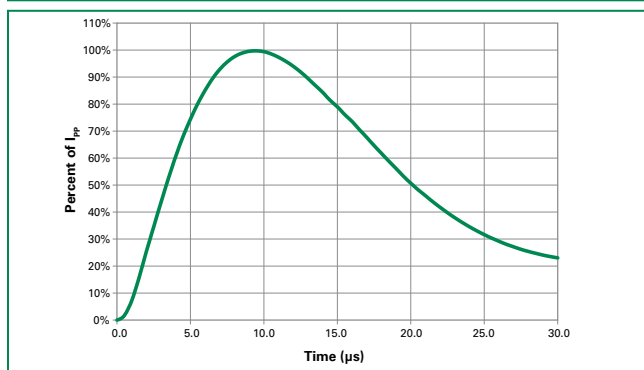
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Forward Voltage Drop	V_F	$I_F = 10mA$		0.8	1.2	V
Reverse Voltage Drop	V_R	$I_R = 1mA$	6.0	7.8	8.5	V
Reverse Standoff Voltage	V_{RWM}	$I_R \leq 1\mu A$			5.0	V
Reverse Leakage Current	I_{LEAK}	$V_R = 5V$			100	nA
Clamp Voltage ¹	V_C	$I_{PP} = 6A$ $t_p = 8/20\mu s$		11.4		V
		$I_{PP} = 7A$ $t_p = 8/20\mu s$		12.0		V
Dynamic Resistance	R_{DYN}	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		0.6		Ω
ESD Withstand Voltage ¹	V_{ESD}	IEC61000-4-2 (Contact Discharge)		± 30		kV
		IEC61000-4-2 (Air Discharge)		± 30		kV
Diode Capacitance ¹	C_D	Reverse Bias=0V		30		pF

Note: ¹ Parameter is guaranteed by design and/or device characterization.

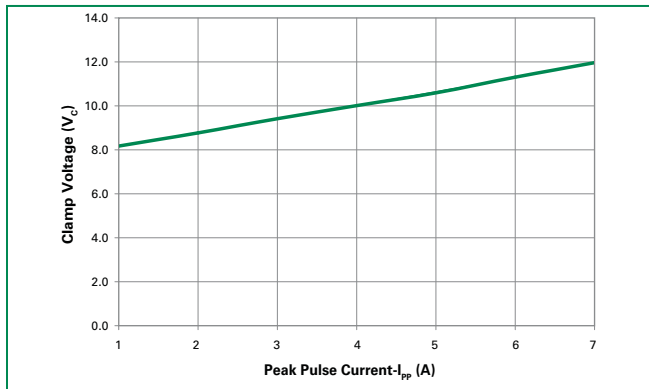
Capacitance vs. Reverse Bias



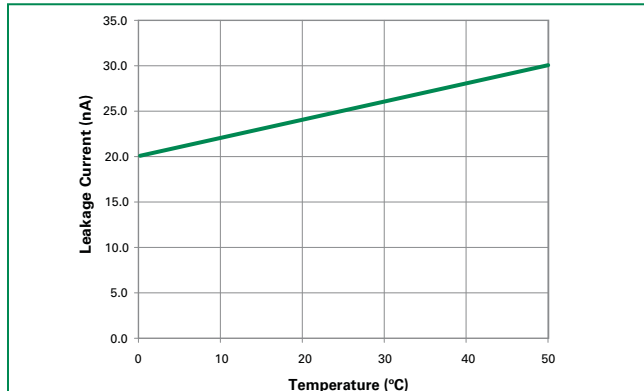
Pulse Waveform



Clamping Voltage vs. I_{PP}

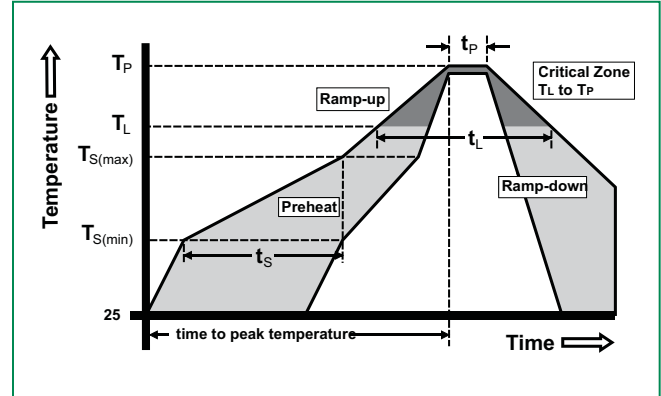


Leakage vs. Temperature

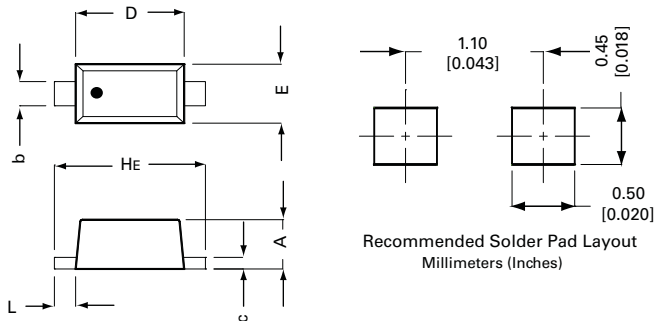


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C

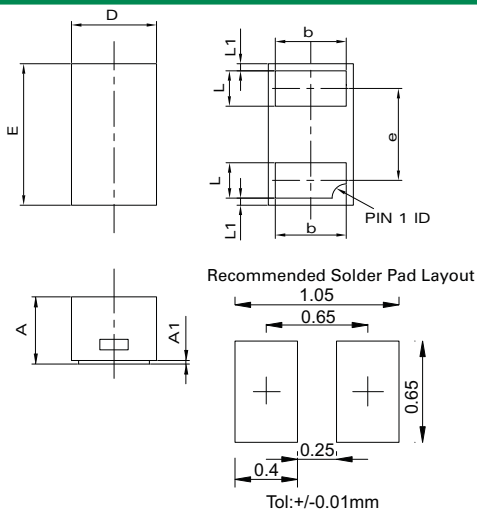


Package Dimensions — SOD723



Symbol	SOD723			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.46	0.65	0.018	0.026
b	0.23	0.35	0.009	0.014
c	0.08	0.13	0.003	0.005
D	0.90	1.10	0.035	0.043
E	0.58	0.64	0.023	0.025
HE	1.37	1.47	0.054	0.058
L	0.15	0.25	0.006	0.010

Package Dimensions — SOD882



Package	SOD882			
JEDEC	MO-236			
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.40	0.50	0.016	0.02
A1	0.00	0.05	0.000	0.002
D	0.55	0.65	0.022	0.026
E	0.95	1.05	0.037	0.041
b	0.40	0.60	0.016	0.024
e	0.65 TYP		0.026 TYP	
L	0.15	0.35	0.006	0.014

Part Numbering System

SP 1003 - 01 * T G

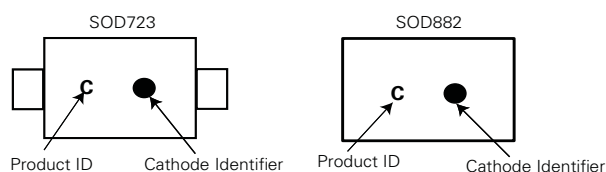
Silicon Protection Array (SPA™)
Family of TVS Diode Arrays
Series

Number of Channels
-01 = 1 Channel

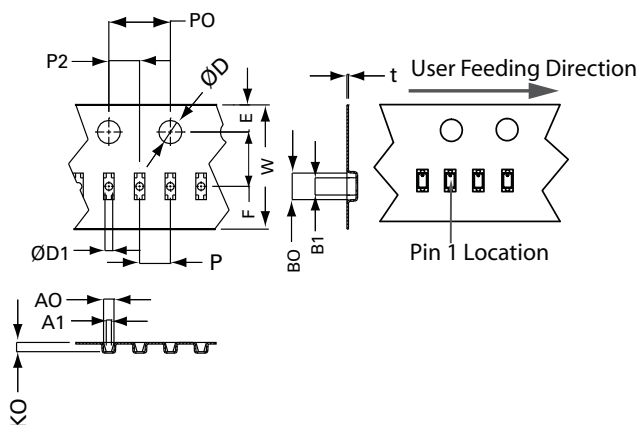
G= Green
T= Tape & Reel

Package
D: SOD723
E: SOD882

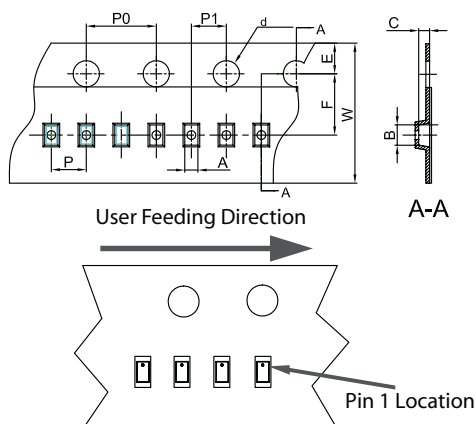
Part Marking System



Embossed Carrier Tape & Reel Specification – SOD723



Embossed Carrier Tape & Reel Specification — SOD882



Product Characteristics

Lead Plating	Pre-Plated Frame or Matte Tin
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substitute Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

Notes :

1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

Ordering Information

Part Number	Package	Marking	Min. Order Qty.
SP1003-01DTG	SOD723	C	8000
SP1003-01ETG	SOD882	C	3000

Symbol	Millimetres		Inches	
	Min	Max	Min	Max
E	1.65	1.85	0.064	0.072
F	3.40	3.60	0.134	0.142
D1	0.45	0.55	0.017	0.021
D	1.50	--	0.060	--
PO	3.90	4.10	0.153	0.161
10PO	40.0+/- 0.20		1.570+/-0.010	
W	7.90	8.20	0.311	0.322
P2/P	1.90	2.10	0.074	0.082
AO	0.60	0.80	0.024	0.032
A1	0.33 REF		0.010 REF	
BO	1.61	1.81	0.063	0.071
B1	1.10 REF		0.040 REF	
KO	0.54	0.78	0.021	0.031
t	--	0.21	--	0.008

Symbol	Millimetres		Inches	
	Min	Max	Min	Max
A	0.65	0.70	0.026	0.028
B	1.10	1.20	0.043	0.047
C	0.50	0.60	0.020	0.024
dØ	1.40	1.60	0.055	0.063
E	1.65	1.85	0.065	0.073
F	3.40	3.60	0.134	0.142
P0	3.90	4.10	0.154	0.161
P	1.90	2.10	0.075	0.083
P1	1.90	2.10	0.075	0.083
W	7.90	8.10	0.311	0.319



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.